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CENTRAL FAX CENTER****SEP 05 2007**

Application Serial No: 10/572,861
Responsive to the Office Action mailed on: April 5, 2007

IN THE SPECIFICATION

Amendments to the Specification:

Please amend the following at page 3, line 13-page 4, line 5 of the specification:

To achieve the above object, ~~the~~ a chip type LED according to ~~claim 1~~ of the present invention comprises an insulating substrate, a light emitting diode chip mounted on an upper surface of the insulating substrate, and a transparent package provided on the upper surface of the insulating substrate to hermetically seal the light emitting diode chip. The light emitting diode chip, including an anode electrode and a cathode electrode, is mounted on the upper surface of the insulating substrate with the anode electrode of the chip oriented downward and the cathode electrode of the chip oriented upward.

~~Claim 2 of the present invention is characterized in that, in the chip type LED of claim 1~~ Preferably, the light emitting diode chip further includes a light emitting layer arranged adjacent to the cathode electrode, while also including a side surface inclined inwardly as the side surface extends from the cathode electrode toward the anode electrode.

~~Claim 3 of the present invention is characterized in that, in the chip type LED of claim 1 or 2~~ Preferably, the upper surface of the insulating substrate is made while at least around the light emitting diode chip.

Please amend the following at page 5, lines 1-12 of the specification:

~~With the~~ In a preferable structure of claim 2 the invention, while keeping the area of the light emitting layer in the light emitting diode chip relatively large, the light generated at the light emitting layer can be emitted through the inwardly inclined side surface without significant attenuation. Therefore, the amount of light emitted laterally is considerably increased.

Further, ~~with the~~ in another preferable structure of claim 3 the invention, the light emitted from the light emitting diode chip toward the insulating substrate is reflected by the white color, whereby the amount of light which travels laterally is further increased.

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IN THE DRAWINGS

The drawings are amended to correct informalities objected to in the present Office Action. Particularly, Replacement Sheets of Figures 1 and 4 are submitted herewith. The Replacement Sheet of Figure 1 is submitted to replace the element number "15b" with the element number "15f" as suggested by the Examiner. The Replacement Sheet of Figure 4 is submitted so as to be designated as prior art as suggested by the Examiner. No new matter is added. Withdrawal of these objections is requested.